100V Nch+Nch Power MOSFET

V_{DSS}	100V
R _{DS(on)} (Max.)	60mΩ
I _D	±12.5A
P _D	14W

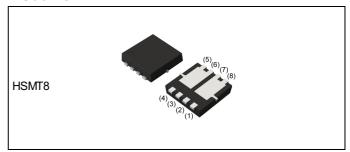
Features

- 1) Low on resistance
- 2) High power small mold package (HSMT8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free
- 5) 100% Rg and UIS tested

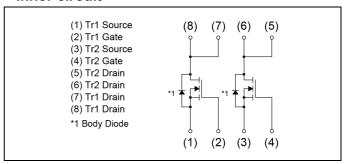
Application

Switching, Motor drives

Outline



•Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Quantity (pcs)	3000
	Taping code	TB1
	Marking	T8KE6H

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	100	V	
Continuous drain current	T _c = 25°C	I _D *1	±12.5	Α
Continuous drain current	$T_a = 25$ °C	I _D	±4.5	Α
Pulsed drain current	I _{DP} *2	±18	А	
Gate - Source voltage		V _{GSS}	±20	V
Avalanche current, single pulse		I _{AS} *3	4.5	Α
Avalanche energy, single pulse	E _{AS} *3	1.6	mJ	
D		P _D *1	14	10/
Power dissipation (total)		P _D *4	2.0	W
Junction temperature	T _j	150	°C	
Operating junction and storage ter	mperature range	T _{stg}	-55 to +150	°C

Thermal resistance

Darameter	Cymbol		Lloit		
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	8.7	°C/W
Thermal resistance, junction - ambient	R _{thJA} *4	-	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

	0 1 1	O Pr		Values			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	100	-	-	V	
Breakdown voltage	ΔV _{(BR)DSS}	I _D = 1mA		62.3		mV/°C	
temperature coefficient	ΔT _j	referenced to 25°C	1	02.3	-	IIIV/ C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$		-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 1mA$		-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$			-4.5	-	mV/°C	
Static drain - source	D *5	V _{GS} = 10V, I _D = 4.5A	-	47	60	0	
on - state resistance	R _{DS(on)} *5	V _{GS} = 6V, I _D = 4.5A	-	59	88	mΩ	
Gate resistance	R_{G}	-	-	2.2	-	Ω	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 5V, I _D = 4.5A	3.3	-	-	S	

^{*1} T_c = 25°C, Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 0.1mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Mounted on a Cu board (40×40×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Daramatar	Cymahal	Conditions		Lloit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	320	-	
Output capacitance	C _{oss}	V _{DS} = 50V	-	75	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	6	-	
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 50V,V _{GS} = 10V	-	9.1	-	
Rise time	t _r *5	I _D = 2.25A	-	6.3	-	
Turn - off delay time	t _{d(off)} *5	$R_L = 22.2\Omega$	-	18.0	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	6.4	-	

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions -		Values			Lloit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total mate about	O *5		V _{GS} = 10V	-	6.3	-	
Total gate charge	Q_g^{*5}	Q g		-	4.2	-	
Gate - Source charge	Q _{gs} *5	I _D = 4.5A	V _{GS} = 6V	-	1.9	-	nC
Gate - Drain charge	Q _{gd} *5			-	1.5	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit		
raianetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T _a = 25°C	-	1	1.67	^
Pulse forward current	I _{SP} *2	1 _a – 25 C	ı	ı	18	Α
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 1.67A	-	-	1.2	٧
Reverse recovery time	t _{rr} *5	I _S = 4.5A, V _{GS} = 0V	-	46	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	80	-	nC

• Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

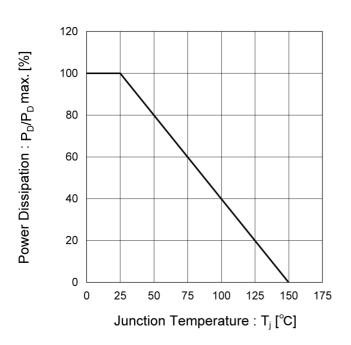
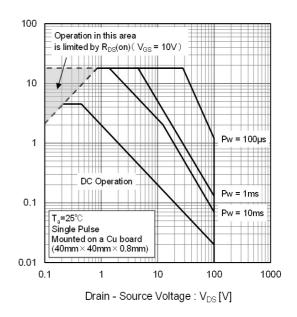


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

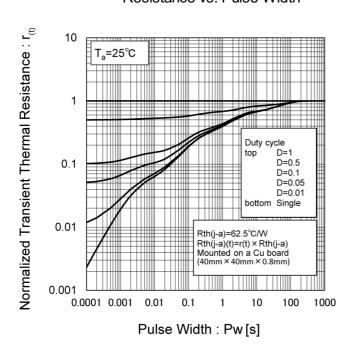
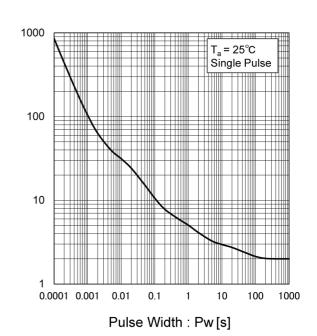


Fig.4 Single Pulse Maximum Power Dissipation



Peak Transient Power: P(W)

Drain Current : I_D [A]

• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

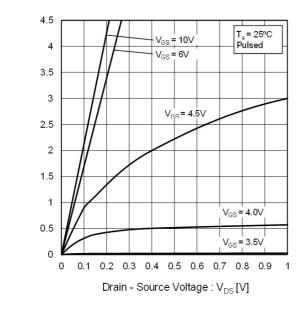
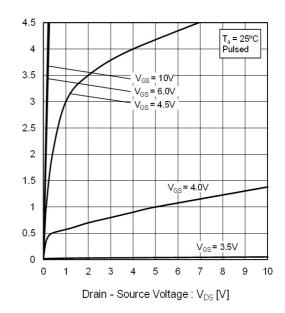
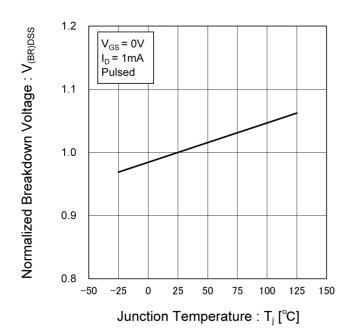


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature



• Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

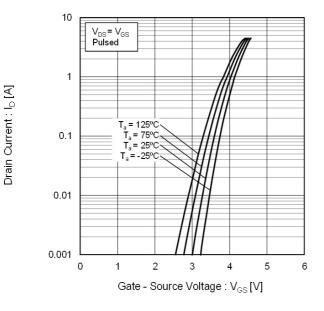


Fig.9 Gate Threshold Voltage vs. Junction Temperature

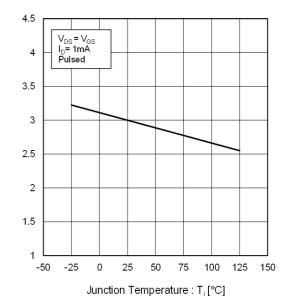
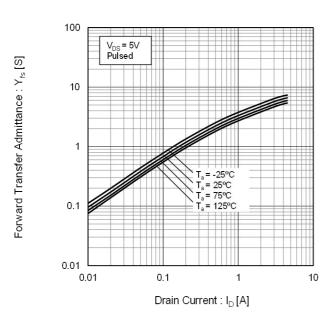


Fig.10 Forward Transfer Admittance vs. Drain Current



Gate Threshold Voltage: V_{GS(th)} [V]

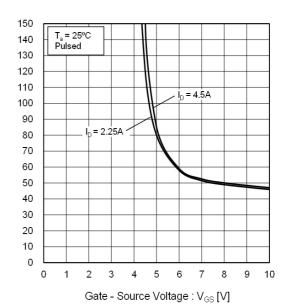
• Electrical characteristic curves

Fig.11 Drain Current Derating Curve

120
100
100
80
60
40
20
0 25 50 75 100 125 150

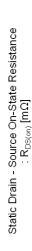
Junction Temperature : T_i [°C]

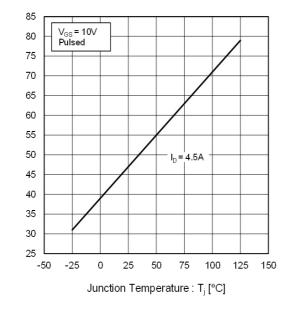
Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance : $R_{D\boxtimes(on)}$ [m $\Omega]$

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





Static Drain - Source On-State Resistance : $R_{DS(on)}$ [m Ω]

• Electrical characteristic curves

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

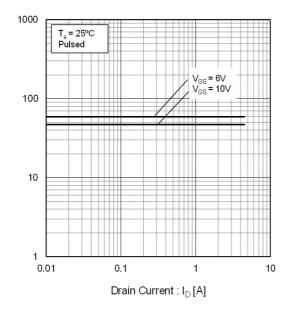
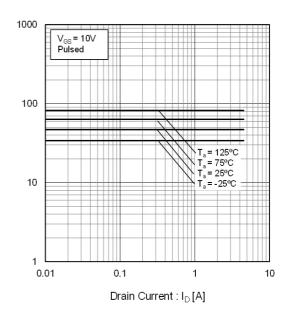
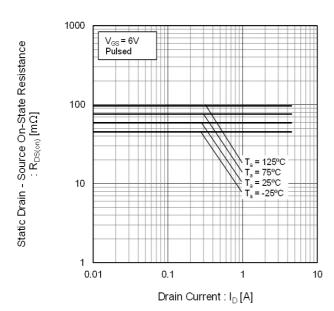


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)



Static Drain - Source On-State Resistance : $R_{\text{DS}(\text{on})} \left[\text{m} \Omega \right]$

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)



Capacitance : C [pF]

Gate - Source Voltage : V_{GS} [V]

• Electrical characteristic curves

Fig.17 Typical Capacitances vs.

Drain - Source Voltage

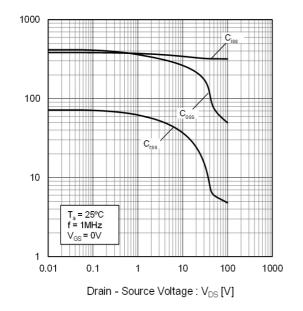


Fig.18 Switching Characteristics

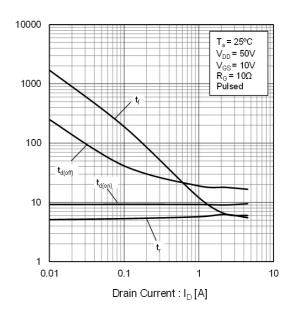


Fig.19 Typical Gate Charge

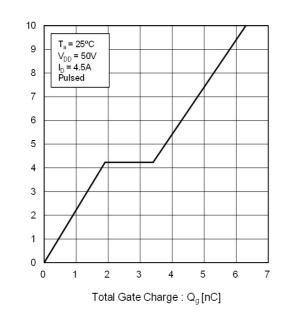
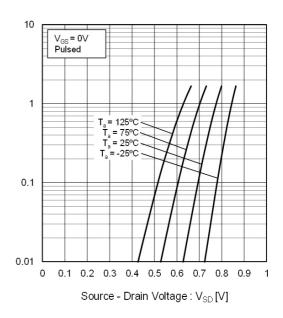


Fig.20 Source Current vs. Source Drain Voltage



Switching Time : t [ns]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

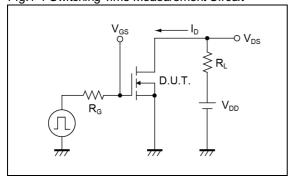


Fig.2-1 Gate Charge Measurement Circuit

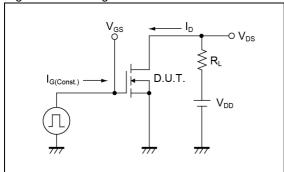


Fig.3-1 Avalanche Measurement Circuit

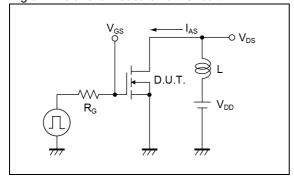


Fig.1-2 Switching Waveforms

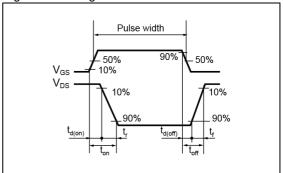


Fig.2-2 Gate Charge Waveform

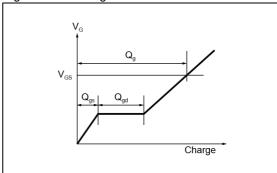
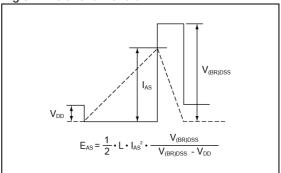


Fig.3-2 Avalanche Waveform

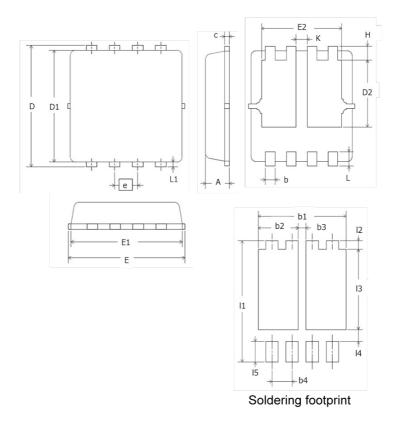


Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

HSMT8 (Dual)



DIM	Milimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	0.70	0.80	0.028	0.031
b	0.25	0.35	0.010	0.014
С	0.10	0.25	0.004	0.010
D	3.25	3.45	0.128	0.136
D1	3.00	3.20	0.118	0.126
D2	1.78	1.98	0.070	0.078
E	3.20	3.40	0.126	0.134
E1	3.00	3.20	0.118	0.126
E2	2.39	2.59	0.094	0.102
е	0.	65	0.0	26
Н	0.30	0.50	0.012	0.020
L	0.30	0.50	0.012	0.020
L1	0.	13	0.0	005
K	0.30	-	0.012	-

DIM	Milimeters	Inches
Dilvi	Nom.	Nom.
l1	3.55	0.140
12	0.25	0.010
13	2.35	0.093
14	0.35	0.014
15	0.60	0.024
b1	2.83	0.111
b2	1.29	0.051
b3	0.25	0.010
b4	0.40	0.016

Dimension in mm / inches



Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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